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(54) CIRCUIT STRUCTURE

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(57) ABSTRACT

Provided is a circuit structure having a novel structure with which the dissipation of heat from a heat generating component can be more reliably promoted with a short heat transfer path. A circuit structure includes: a heat generating component; bus bars connected to connection portions of the heat generating component; an insulating base member configured to hold the heat generating component and the bus bars; and a coolant flow path provided inside the base member and through which a coolant flows, the bus bars being in thermal contact with the coolant flow path.